



## N-channel Power MOSFET

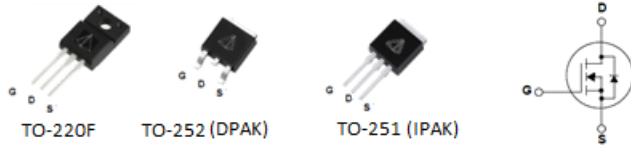
PRODUCT SUMMARY	
V <sub>DS</sub> (V) at T <sub>J</sub> max.	700
R <sub>DS(on)</sub> max. at 25°C (mΩ)	V <sub>GS</sub> =10V   360
Q <sub>g</sub> max. (nC)	30
Q <sub>gs</sub> (nC)	8.5
Q <sub>gd</sub> (nC)	7.5
Configuration	single

### Features

- New Technology For High Voltage Device
- ID=11.5A(Vgs=10V)
- Ultra Low Gate Charge
- Improved dv/dt Capability
- RoHS Compliant

### Applications

- Switching Mode Power Supplies (SMPS)
- Power factor correction ( PFC )
- Uninterruptible Power Supply ( UPS )



ORDERING INFORMATION			
Device	SPC65R360G	SPE65R360G	SPD65R360G
Device Package	TO-220F	TO-251	TO-252
Marking	65R360G		

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25°C, unless otherwise noted)				
Parameter	Symbol	Limit		Unit
		SPC65R360G	SPE65R360G SPD65R360G	
Drain to Source Voltage	V <sub>DSS</sub>	650	650	V
Continuous Drain Current (@T <sub>C</sub> =25°C)	I <sub>D</sub>	11.5 <sup>(1)</sup>	11.5 <sup>(1)</sup>	A
Continuous Drain Current (@T <sub>C</sub> =100°C)		7 <sup>(1)</sup>	7 <sup>(1)</sup>	A
Drain current pulsed <sup>(2)</sup>	I <sub>DM</sub>	42 <sup>(1)</sup>	42 <sup>(1)</sup>	A
Gate to Source Voltage	V <sub>GS</sub>	±30	±30	V
Single pulsed Avalanche Energy <sup>(3)</sup>	E <sub>AS</sub>	144	144	mJ
MOSFET dv/dt ruggedness (@V <sub>DS</sub> =0~400V)	dv/dt	25	25	V/ns
Peak diode Recovery dv/dt <sup>(4)</sup>	dv/dt	15	15	V/ns
Total power dissipation (@T <sub>C</sub> =25°C)	P <sub>D</sub>	32.6	101	W
Derating Factor above 25°C		0.26	0.97	W/°C
Operating Junction Temperature & Storage Temperature	T <sub>STG</sub> , T <sub>J</sub>	-55 to + 150		°C
Maximum lead temperature for soldering purpose	T <sub>L</sub>	260		°C
Mounting torque <sup>(5)</sup>		0.4~0.6		N.m

Notes

1. Drain current is limited by maximum junction temperature.
2. Repetitive rating : pulse width limited by junction temperature.
3. L = 72mH, I<sub>AS</sub> = 2A, V<sub>DD</sub> = 50V, R<sub>G</sub>=25Ω, Starting at T<sub>J</sub> = 25°C
4. I<sub>SD</sub> ≤ I<sub>D</sub>, di/dt = 100A/us, V<sub>DD</sub> ≤ BV<sub>DSS</sub>, Starting at T<sub>J</sub> =25°C
5. Mounting consideration for TO220 Fullpack:  
M3 screw plus flat washer is suggested, free of burr between devices and contact area,  
the devices are to be mounted to a hole not larger than 3.6mm in contact diameter (chamfer included).



THERMAL CHARACTERISTICS				
Parameter	Symbol	Value		Unit
		SPC65R360G	SPE65R360G SPD65R360G	
Thermal resistance, Junction to case	$R_{thjc}$	3.83	1.24	°C/W
Thermal resistance, Junction to ambient	$R_{thja}$	80	62	°C/W

ELECTRICAL CHARACTERISTICS ( $T_C = 25^\circ\text{C}$ unless otherwise specified )						
Parameter	Symbol	Test conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
Drain to source breakdown voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	650			V
Breakdown voltage temperature coefficient	$\Delta BV_{DSS} / \Delta T_J$	$I_D=250\mu A$ , referenced to $25^\circ\text{C}$		0.7		V/°C
Drain to source leakage current	$I_{DSS}$	$V_{DS}=650V, V_{GS}=0V$			1	uA
		$V_{DS}=650V, T_C=125^\circ\text{C}$			10	uA
Gate to source leakage current, forward	$I_{GSS}$	$V_{GS}=30V, V_{DS}=0V$			100	nA
Gate to source leakage current, reverse		$V_{GS}=-30V, V_{DS}=0V$			-100	nA
<b>On Characteristics</b>						
Gate threshold voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2	3	4	V
Drain to source on state resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=6A$		300	360	mΩ
Forward Transconductance	$G_{fs}$	$V_{DS}=20V, I_D=6A$		8		S
<b>Dynamic Characteristics</b>						
Input capacitance	$C_{iss}$	$V_{GS}=0V, V_{DS}=50V, f=1\text{MHz}$		1200		pF
Output capacitance	$C_{oss}$			45		
Reverse transfer capacitance	$C_{rss}$			3.5		
Turn on delay time	$t_{d(on)}$	$V_{DS}=380V, I_D=11.5A, R_G=18\Omega, V_{GS}=10V$		11		ns
Rising time	$t_r$			5		
Turn off delay time	$t_{d(off)}$			50		
Fall time	$t_f$			5		
Total gate charge	$Q_g$	$V_{DS}=480V, V_{GS}=10V, I_D=11.5A$		24	30	nC
Gate-source charge	$Q_{gs}$			8.5		
Gate-drain charge	$Q_{gd}$			7.5		

SOURCE TO DRAIN DIODE RATINGS CHARACTERISTICS						
Parameter	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Continuous source current	$I_S$	Integral reverse p-n Junction diode in the MOSFET			11.5	A
Pulsed source current	$I_{SM}$				42	A
Diode forward voltage drop.	$V_{SD}$	$I_S=11.5A, V_{GS}=0V$		0.9	1.3	V
Reverse recovery time	$T_{rr}$	$I_S=11.5A, V_{GS}=0V, dl_f/dt=100A/\mu s$		220		ns
Reverse recovery Charge	$Q_{rr}$				2.2	



Fig1. Output characteristics

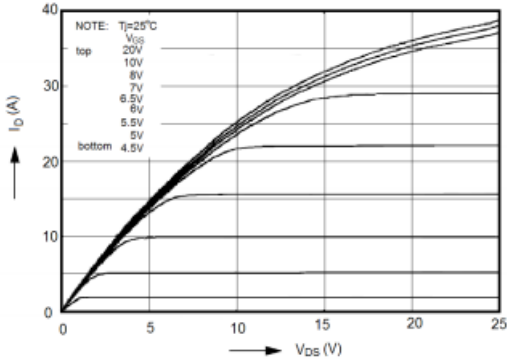


Fig2. Maximum Drain Current vs. Case Temperature

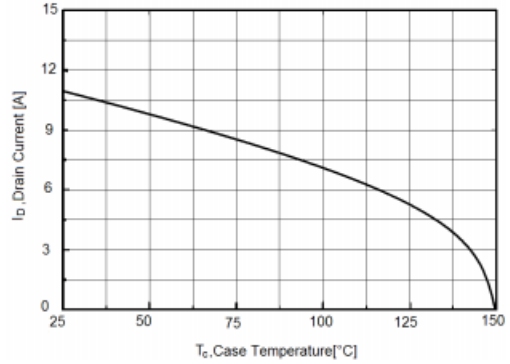


Fig3. Gate charge characteristics

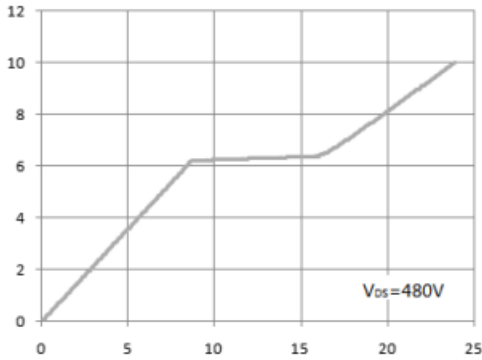


Fig 4. Capacitance Characteristics

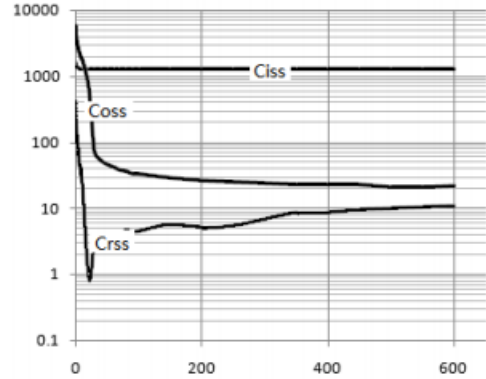


Fig 5.  $R_{DS(ON)}$  vs junction temperature

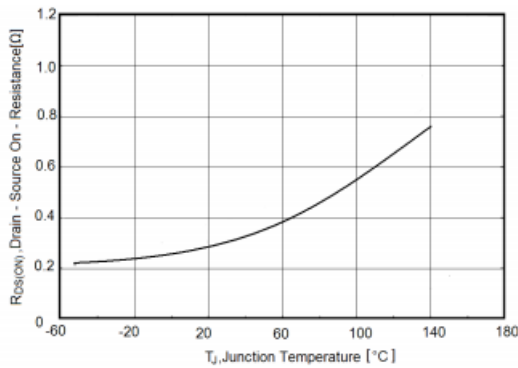


Fig 6. Temperature vs. Drain-to-Source Voltage

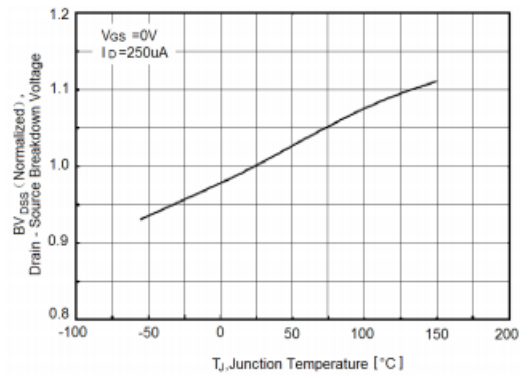




Fig 7 . Safe operating area (TO-220F)

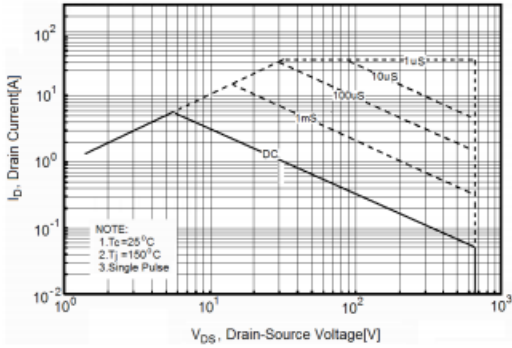


Fig 8 . Transient thermal impedance (TO-220F)

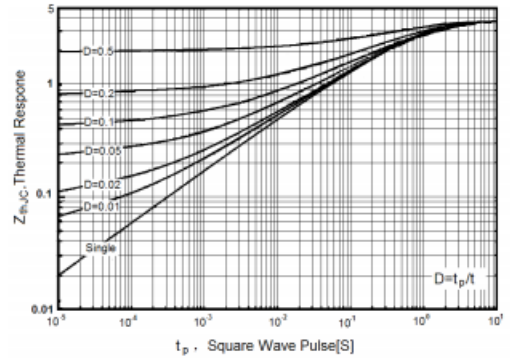


Fig 9 . Safe operating area (TO-251/252)

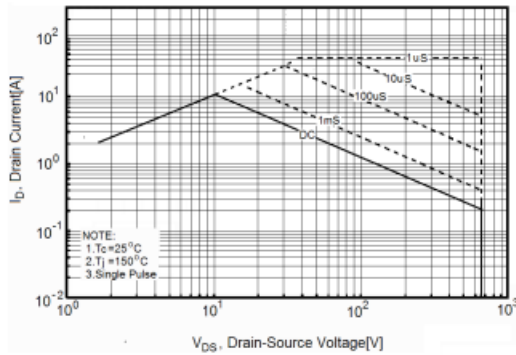


Fig 10 . Transient thermal impedance (TO-251/252)

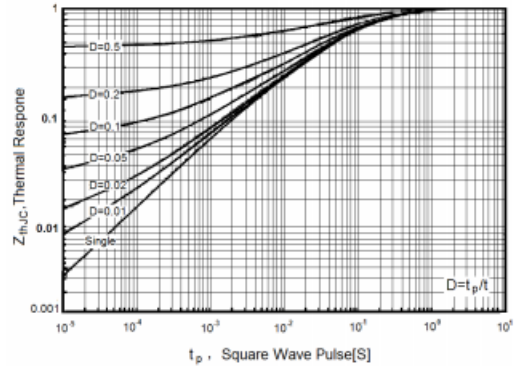


Fig 11. Forward characteristics of reverse diode

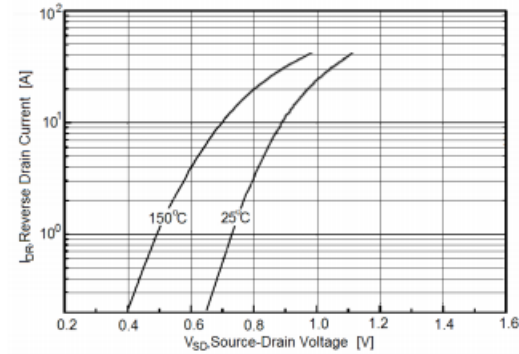


Fig 12 . Transfer characteristics

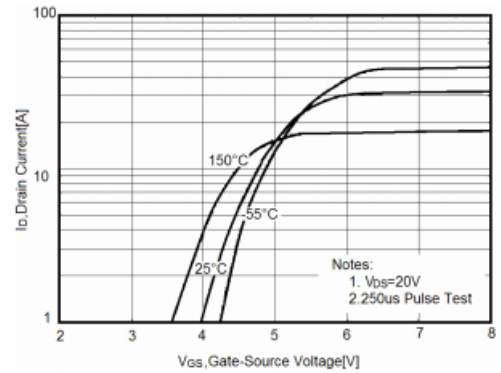


Fig 13. Gate charge test circuit & waveform

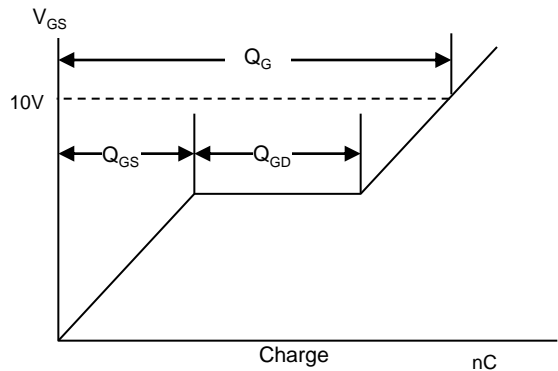
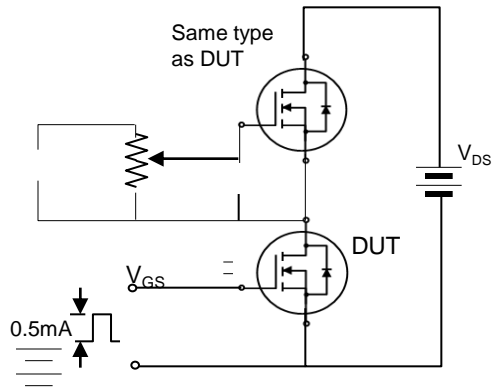


Fig 14. Switching time test circuit & waveform

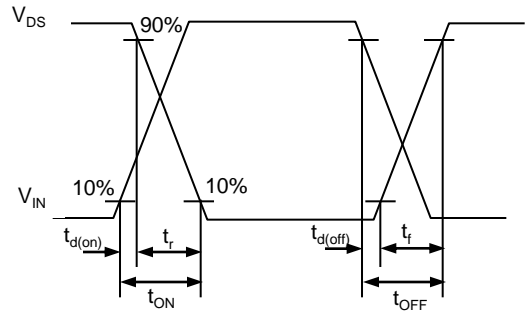
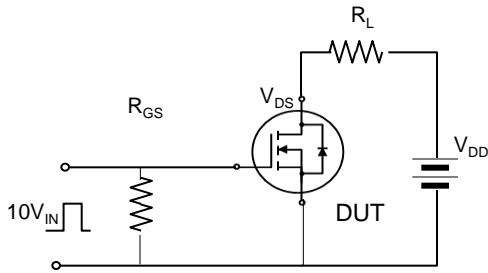


Fig 15. Unclamped Inductive switching test circuit & waveform

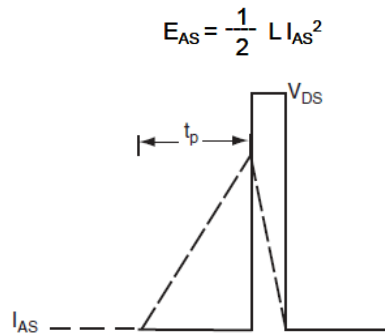
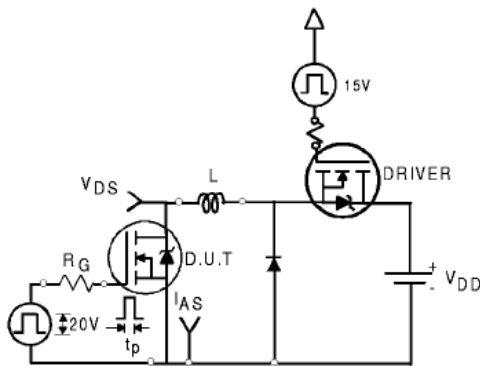
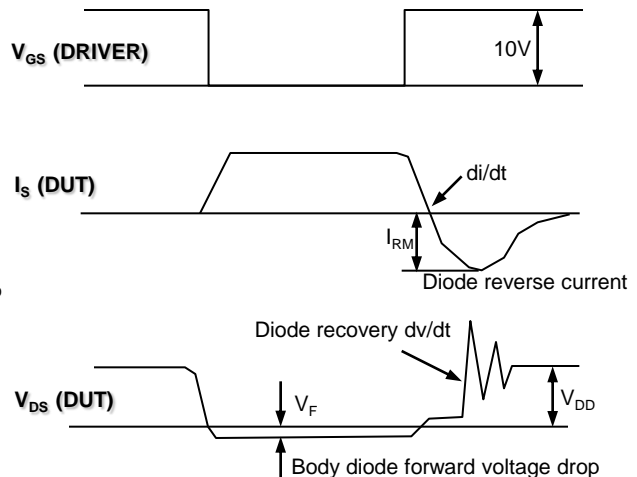
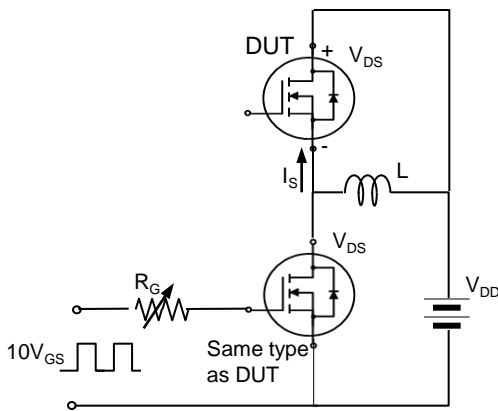


Fig 16. Peak diode recovery dv/dt test circuit & waveform



\*. dv/dt controlled by RG  
 \*. IS controlled by pulse period



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